

AA-DUCT 916LC

Room Temperature Conductive Flexible Epoxy Adhesive

Technical Product Bulletin

PRODUCT DESCRIPTION:

AA-DUCT 916LC is an electrically conductive, low cost silver filled epoxy formulation recommended for electronic bonding, coating, and sealing applications that require high flexibility coupled with good electrical and mechanical properties.

AA-DUCT 916LC is two-part, smooth paste adhesive and free of solvents and copper or carbon additives. It develops strong, durable, resilient, electrically and thermally conducting bonds and coatings between many different and dissimilar materials such as metals, ceramics, glass and plastic insulates.

AA-DUCT 916LC cures at room temperature and has been used extensively in such diversified applications as, microwave EMI and RFI shielding, in the assembly or repair of printed circuit boards, wave guides, electronic modules, flat cable, high frequency shields, connections, and circuitry and as a cold solder. This unique formulation offers ease in handling due to its creamy consistency and versatile application by hand, automatic dispenser, silk-screening, transfer or stamping techniques.

PRODUCT INFORMATION

Appearance	Tan color	
Cure Type	Room temperature or Heat cure	
Benefits	high strength Perfect bond Cold solder for high-sensitive components EMI & RFI Shielding	
Mix Ratio by weight	100:115 / Resin: Hardener	
Substrates	Excellent choice aluminum, copper, magnesium, steel, bronze, nickel, kovar, ceramic, glass, phenolic and G-10 epoxy glass boards.	
Operating Temperature	-60 to 145 °C	

UNCURED PROPERTIES:

Viscosity @ 25 °C cps	Paste
Specific Gravity, mixed	2.85
Reactive solids contents, %	100
Pot Life	1.5 hours

CURING SCHEDULE:

2 hours	@ 65°C
24 to 48 hours	@ 25°C
CURED PROPERTIES:	
Hardness, Shore D	60
Volume Resitivity ohm. cm	<0.002

GENERAL INFORMATION:

For safe handling information on this product, consult the Safety Data Sheet, (SDS).

HOW TO USE:

1. Carefully clean and dry all surfaces to be bonded

2. Apply AA-DUCT 916LC completely mixed adhesive to the preparedsurfaces, and gently press these surfaces together. Contact pressure is adequate for strong, reliable bonds; however, maintain contact until adhesive is completely cured

3. Some separation of components is common during shipping and storage. For this reason, it is recommended that the contents of the shipping container be thoroughly mixed prior to use

4. Some ingredients in this formulation provided may crystallize whensubjected to low temperature storage. A gentle warmingcycle of 52°C for 30 minutes prior to mixing componentsmay be necessary. Crystallized epoxy components donot react as well as liquid components and should beredissolved prior to use for best results

AVAILABILITY

This epoxy can be supplied in many different packages.